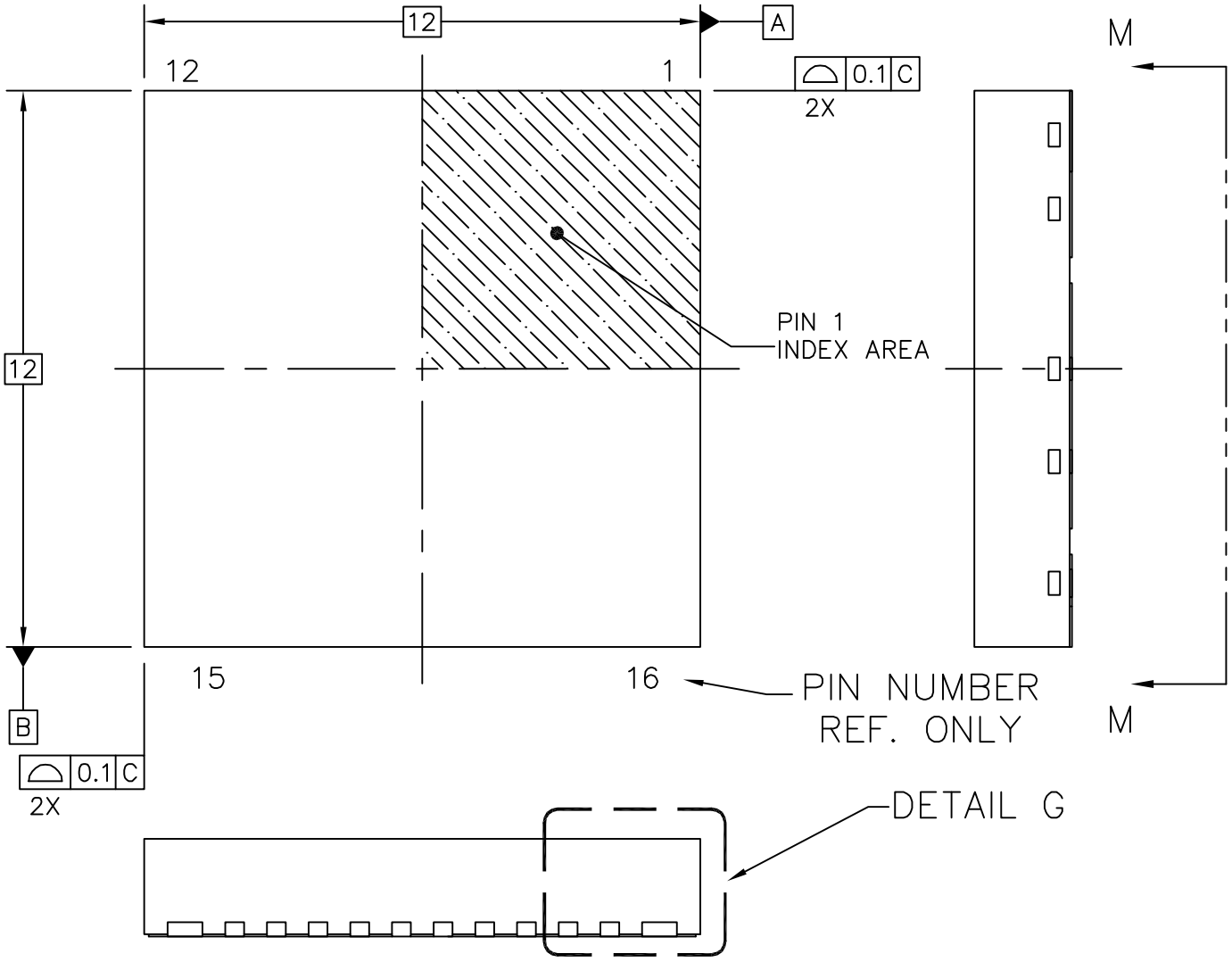
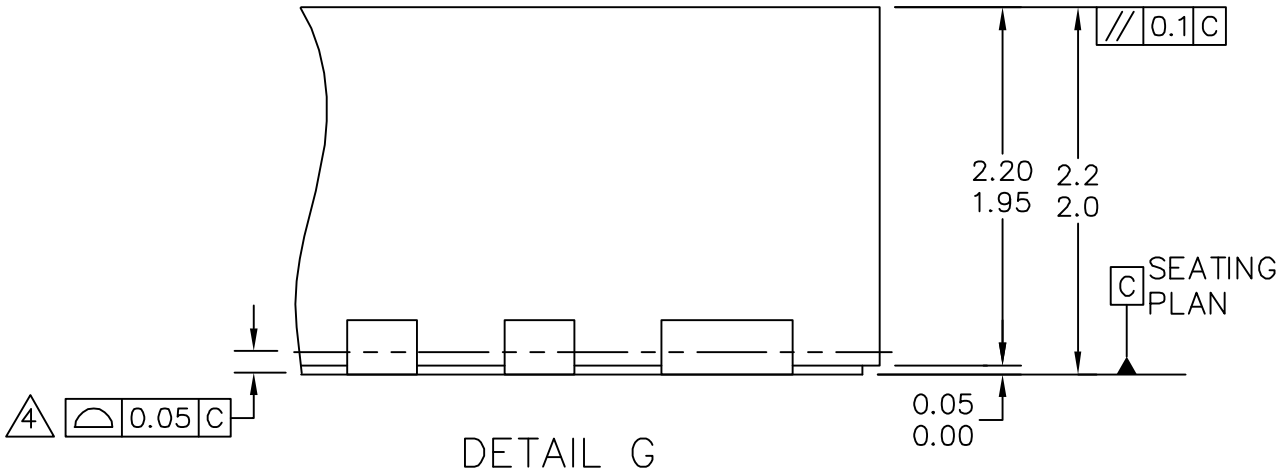
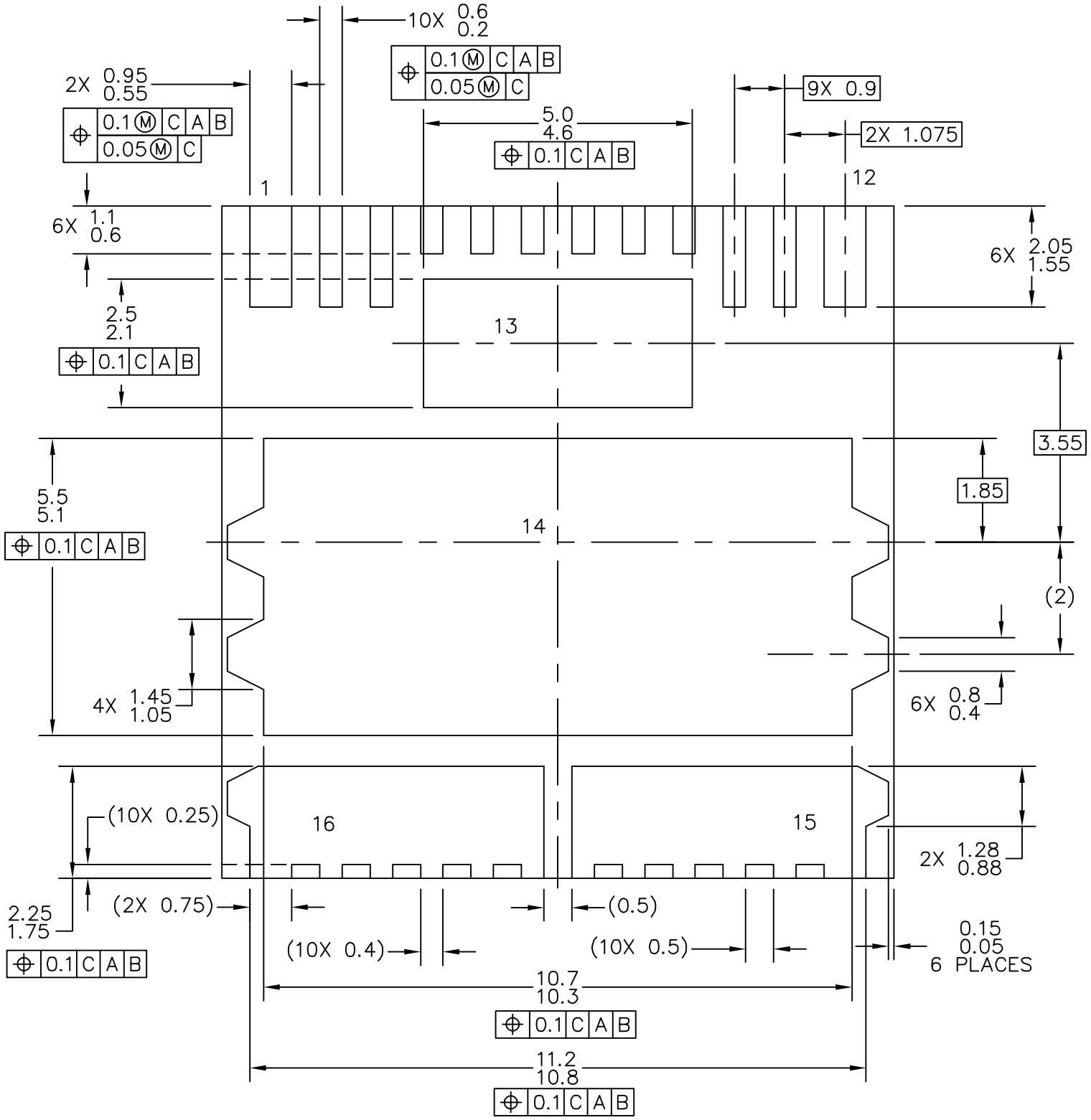




MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

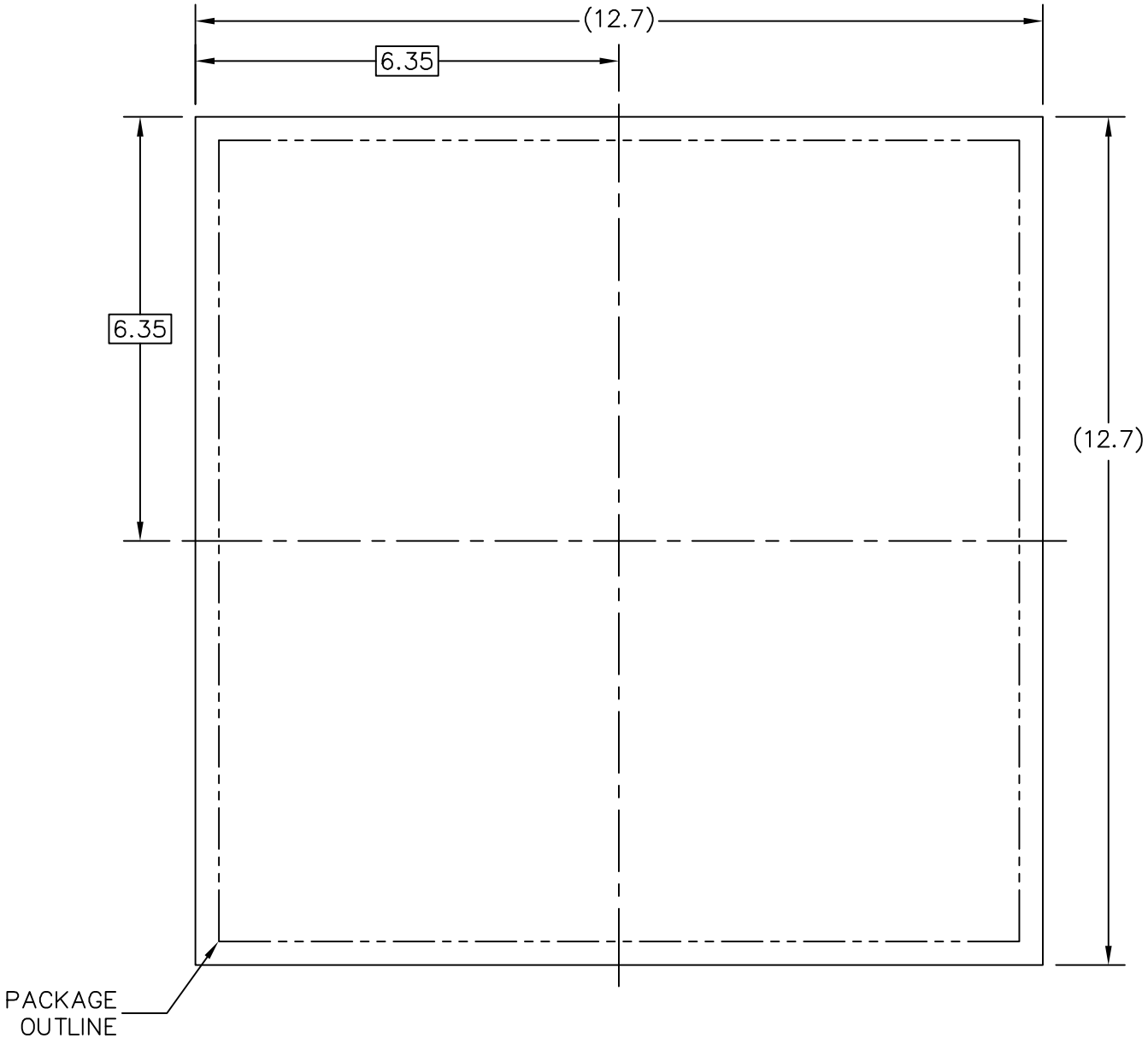
TITLE: POWER QUAD FLAT NON-LEADED PACKAGE (PWR QFN) 16 TERMINAL, 0.9 PITCH(12X12X2.1)	DOCUMENT NO: 98ARL10521D	REV: D
	CASE NUMBER: 1402-03	21 SEP 2011
	STANDARD: NON-JEDEC	



VIEW M–M

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: POWER QUAD FLAT NON–LEADED PACKAGE (PWR QFN) 16 TERMINAL, 0.9 PITCH(12X12X2.1)	DOCUMENT NO: 98ARL10521D	REV: D
	CASE NUMBER: 1402–03	21 SEP 2011
	STANDARD: NON–JEDEC	



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 1

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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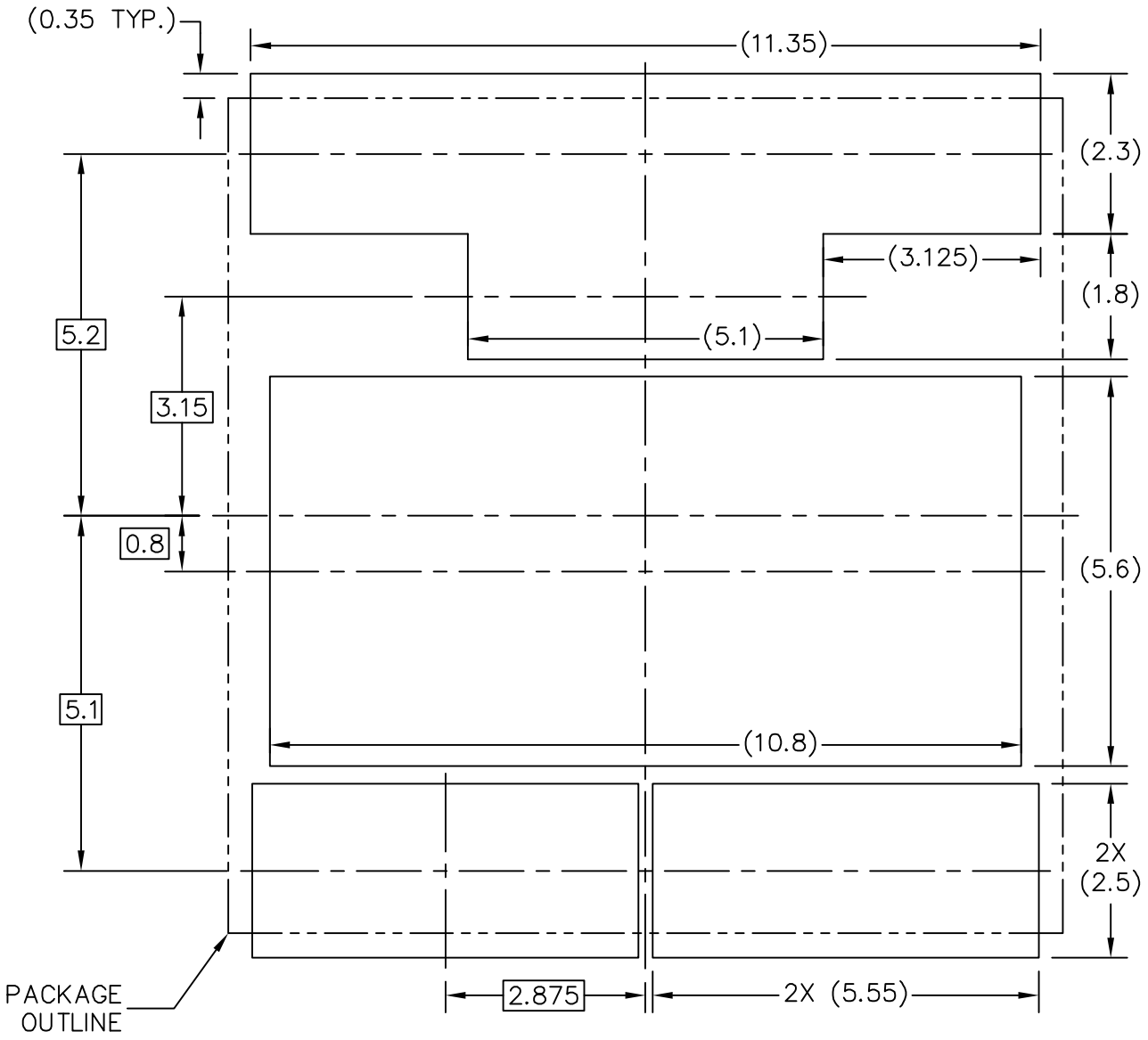
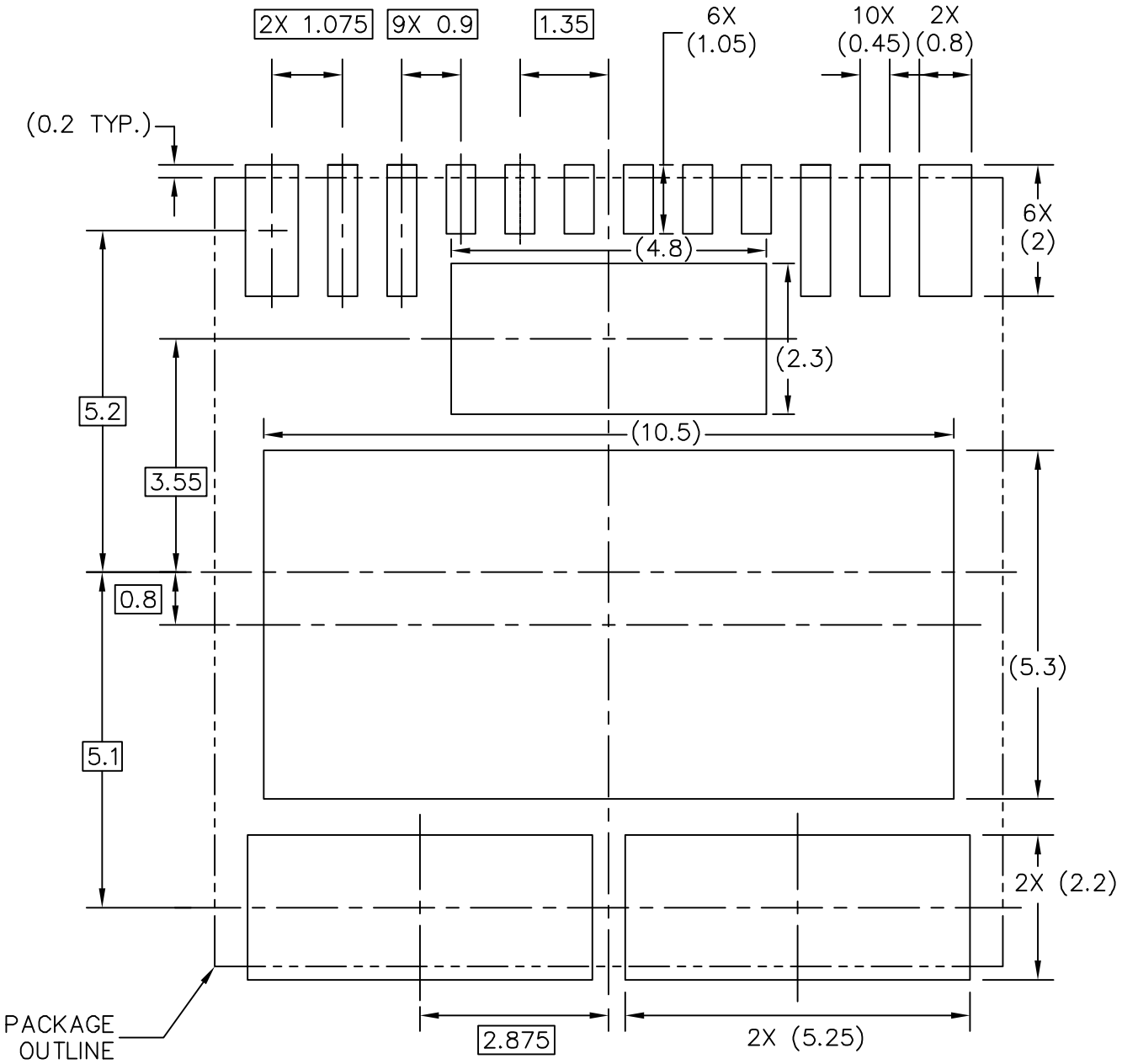


PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 2

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: POWER QUAD FLAT NON–LEADED PACKAGE (PWR QFN) 16 TERMINAL, 0.9 PITCH(12X12X2.1)	DOCUMENT NO: 98ARL10521D	REV: D
	CASE NUMBER: 1402–03	21 SEP 2011
	STANDARD: NON–JEDEC	

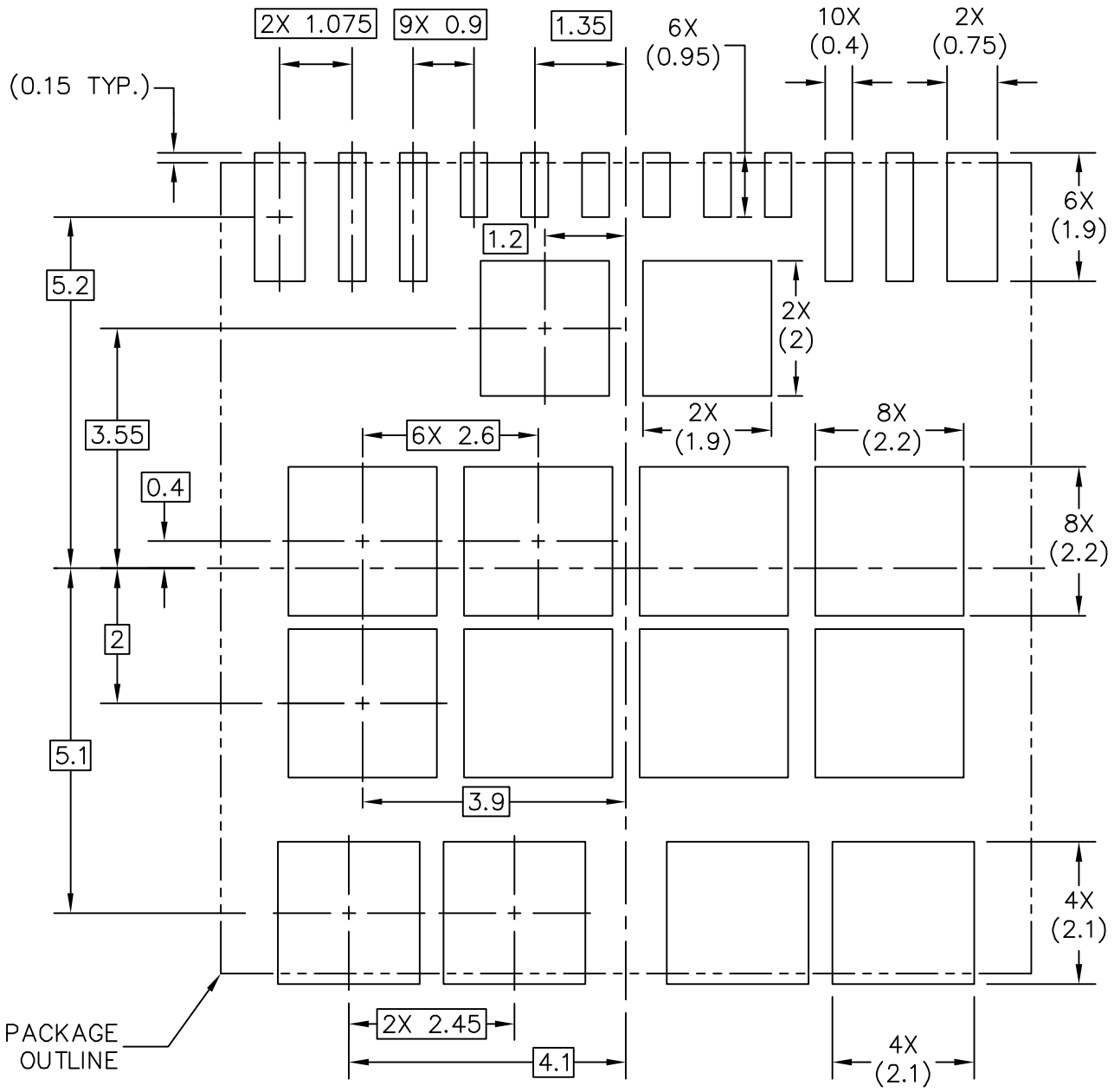


PCB CU GUIDELINES – I/O PADS & SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE: POWER QUAD FLAT NON–LEADED PACKAGE (PWR QFN) 16 TERMINAL, 0.9 PITCH(12X12X2.1)	DOCUMENT NO: 98ARL10521D	REV: D
	CASE NUMBER: 1402–03	21 SEP 2011
	STANDARD: NON–JEDEC	



SOLDER PASTE STENCIL GUIDELINES

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

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	CASE NUMBER: 1402-03	21 SEP 2011
	STANDARD: NON-JEDEC	

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFP–N.
4. COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP SHOULD BE 0.25MM.

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